



With the arrival of the AI era, chip heat generation in liquid cooling products has dramatically increased. As a result, Thermal Interface Materials (TIM) between chips and cold plates are increasingly utilizing PCM (Phase Change Material).

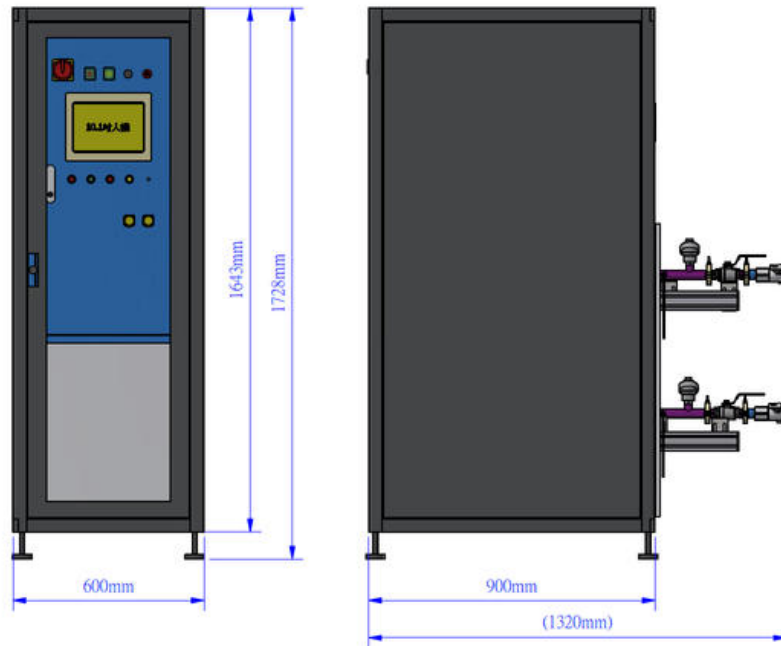
To address potential thermal performance issues caused by assembly tolerances where initial-state PCM pads may not achieve complete contact with chips, thereby compromising thermal conduction efficiency.

Consequently, we have specifically engineered a heat exchange system (SA-162B) designed exclusively for **Nvidia** new TIM Settling process. The operational characteristic parameters have been fully verified, and this product is being utilized by all GB200 OEM customers for their L10 TIM Settling process.

PCM Heating Circulating Bath With Heat Exchange Measurements



Product Dimensions



Key Features

- Superior Temperature Control Performance with $\pm 1^{\circ}\text{C}$ Precision
- Constant temperature and pressure control
- All liquid pipelines use SUS304 stainless steel
- All piping uses welding process to prevent various leakages
- Two-stage dry-run prevention mechanism (software/hardware)
- Automatic operation mode effectively increases production efficiency
- Built-in data collection and 3-month storage
- Optional data reporting system available for MES integration with factory systems
- Modular design for rapid installation



Product Performance

Category	Value
Heating Capacity	0-5.0kw
Power consumption	6.0kw
System Power	220 VAC 30A 60 Hz
Operating Temperature Range	40-80°C
Operating Flow Range	10-40 LPM
Pressure Drop Measurement Range	0-30Kpa
Return pipe filtration device	10" 20um
Heating tank material	SUS 304
Heating tank volume	90L
Outline size (L x W x H)	600 x 900 x 1728 mm
Dry Weight	250 kg
Loop Port Size	FD83 1"/FD83 2"

System Performance

